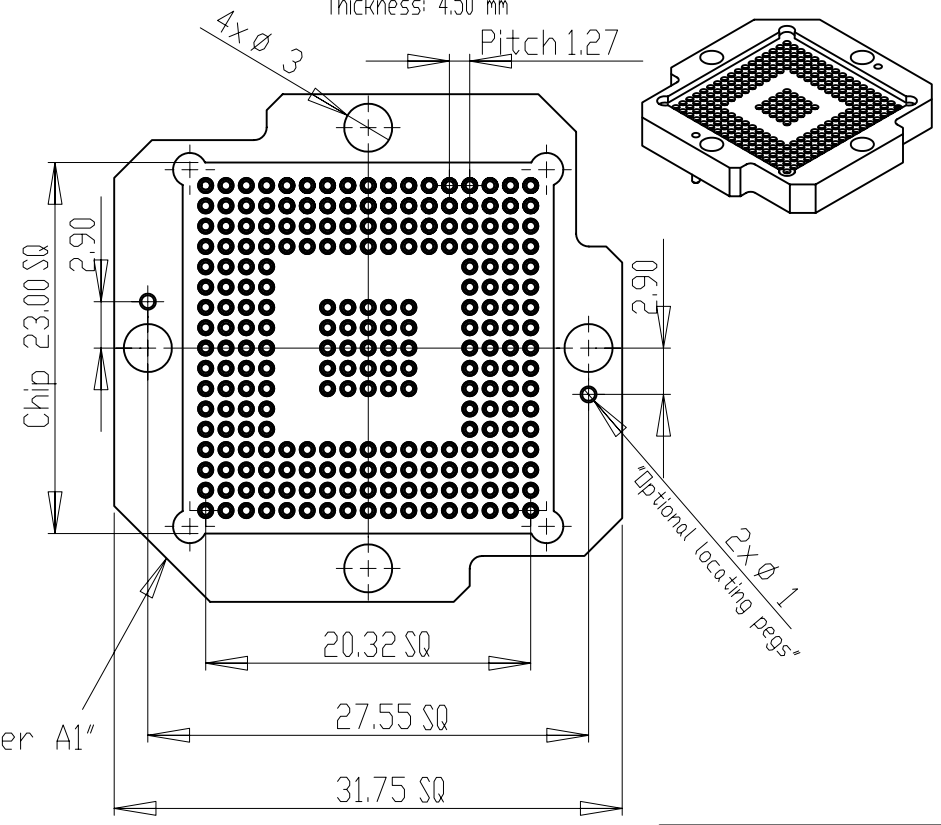
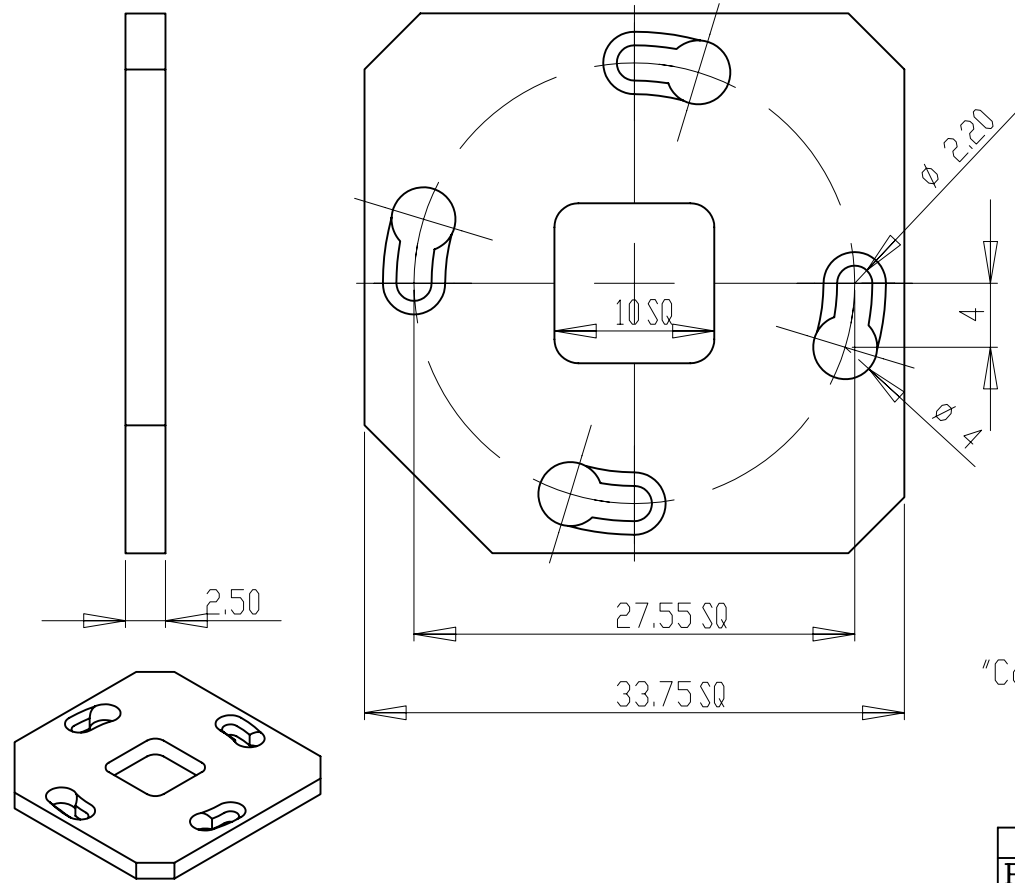


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	06/06/07	H.N.

Socket
Material: TG 200
Thickness: 4.50 mm

SKT2937

Retention frame
Material: Epoxy FR4

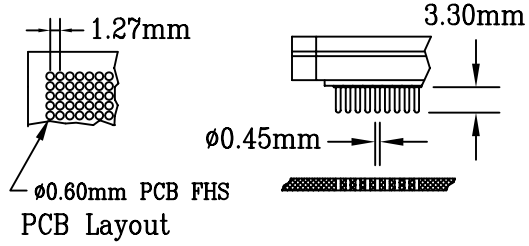
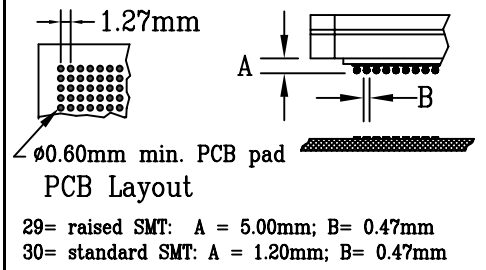


PCB holes for locating pegs
- $\phi 1.10 \pm 0.02$
Note: Locating pegs can also be soldered to PCB if plated-thru holes are provided

RECOMMENDED PAD LAYOUT

SURFACE MOUNT STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = SM	XX = SR
YY = 30	YY = 29

SOLDERTAIL = THRU HOLE STYLE
XX = ET
YY = 70



PACKAGE SPECIFICATIONS

PIN COUNT	= 233
LEAD PITCH	= 1.27mm
GRID SIZE	= 17X17
PACKAGE SIZE	= 23.00mm SQ
IC BALL DIA	= 1.00mm MAX.
BALL HEIGHT	= 0.70mm MAX.

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
SURFACE FINISH:
GENERAL TOLERANCES: ± 0.10
LINEAR:
ANGULAR:

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED



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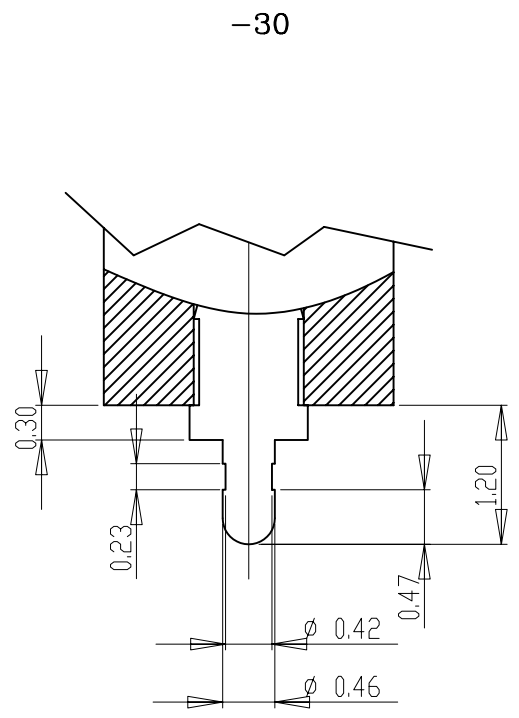
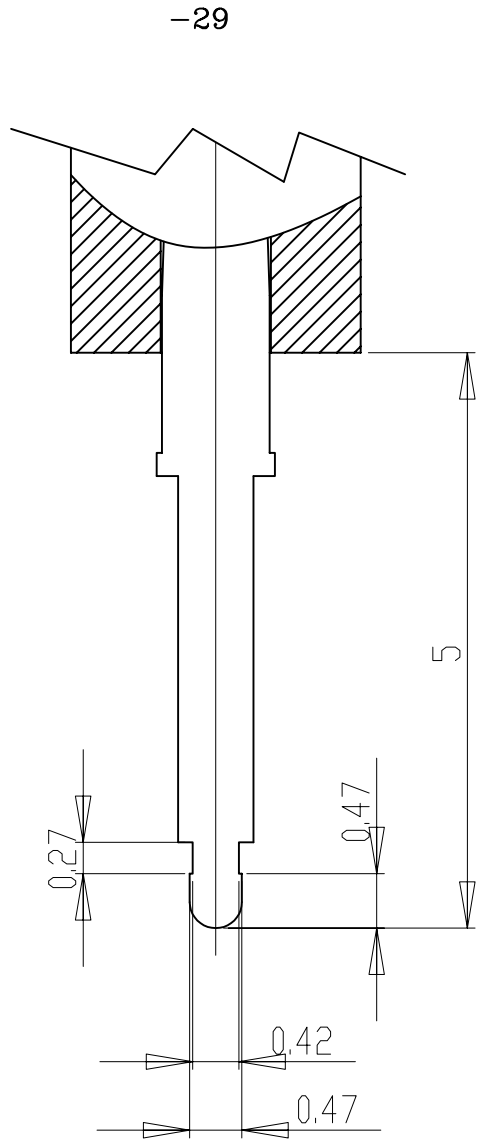
2344 Walsh Avenue, Bldg.F
Santa Clara, Ca 95051
TEL:(408)982-0660
FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 06/06/07	REVISION: A	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.	ITEM: S-BGA-17-233-XX	
Scale N/A DO NOT SCALE DRAWING			DESCRIPTION: BPW-233-2BG017-YY

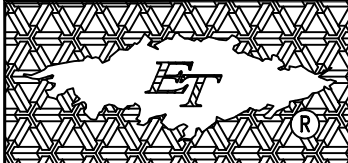
All Dimensions Are Nominal For A 1.27mm Pitch BGA Package

REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	06/28/06	H.N.

ET-1.27mm



ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED



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SHEET: 1 OF 1	DATE: 06/28/06	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: 1.27mm PITCH PIN	
Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION: 1.27mm PITCH PIN	